

Transient Voltage Suppressor

Features

- Small Body Outline Dimensions
- Low Body Height: 0.024" (0.6 mm) nom
- Bidirectional ESD protection of one I/O line
- Low clamping voltage
- Working voltage: 5V
- Low leakage current
- Solid-state silicon-avalanche technology



IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)

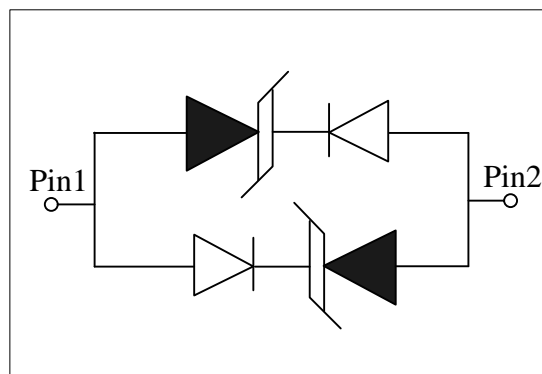
Mechanical Characteristics

- JEDEC SOD-523 package
- Marking : Marking Code
- Packaging : Tape and Reel per EIA 481
- RoHS Compliant

Applications

- Cellular Handsets & Accessories
- Personal Digital Assistants (PDAs)
- Notebooks & Handhelds
- Portable Instrumentation
- Digital Cameras
- MP3 players

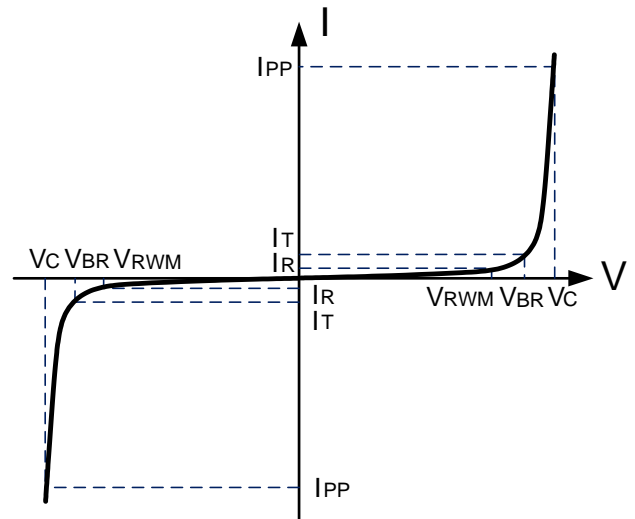
Schematic & PIN Configuration



Absolute Maximum Rating			
Rating	Symbol	Value	Units
Operating Temperature	T_J	-55 to + 125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



Electrical Characteristics

WE05D5UC-B						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				5.0	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	6.0		10.0	V
Reverse Leakage Current	I_R	$V_{RWM}=5V, T=25°C$			200	nA
ESD Clamping Voltage ¹	V_C	$I_{PP} = 4A$ $t_p = 0.2/100ns$		11.9		V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 16A$ $t_p = 0.2/100ns$		23.4		V
Dynamic Resistance ^{1,2}	R_{DYN}	TLP=0.2/100ns		0.95		Ω
Junction Capacitance	C_j	$V_R=0V, f=1MHz$		0.5	1.0	pF

Notes : 1、 TLP Setting : $t_p=100ns, t_r=0.2ns, I_{TLP}$ and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.
 2、 Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using "Best Fit".

Typical Characteristics

Figure 1: Normalized Junction Capacitance vs. Reverse Voltage

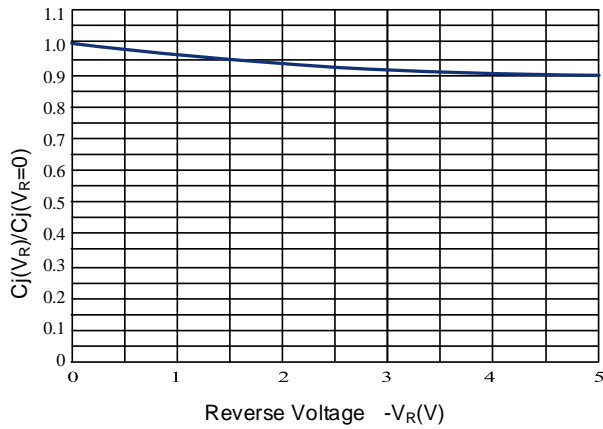


Figure 2: Power Derating Curve

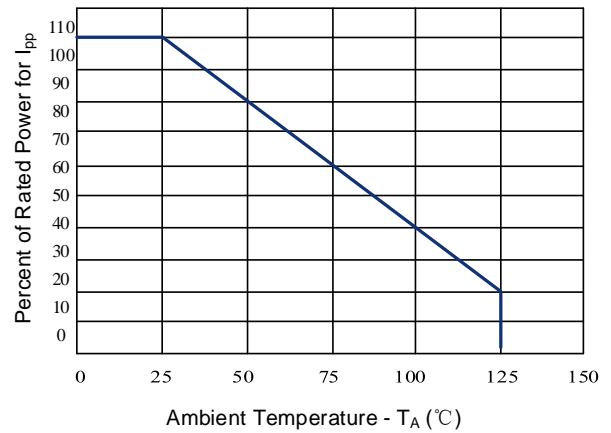


Figure 3: TLP Positive I-V Curve

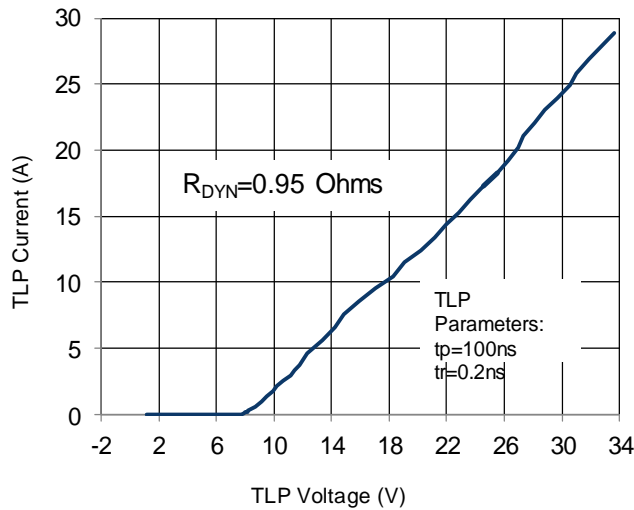
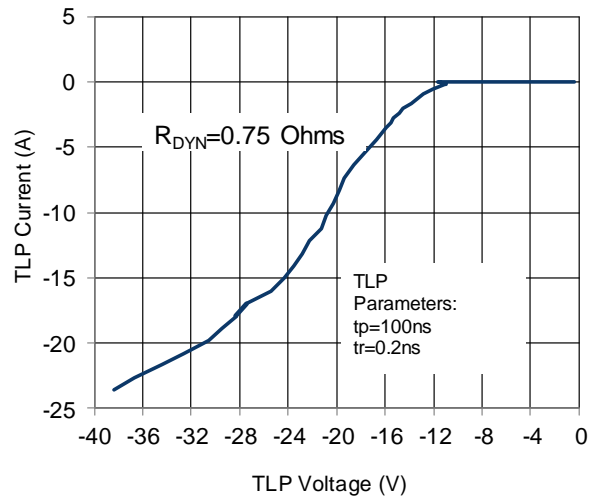
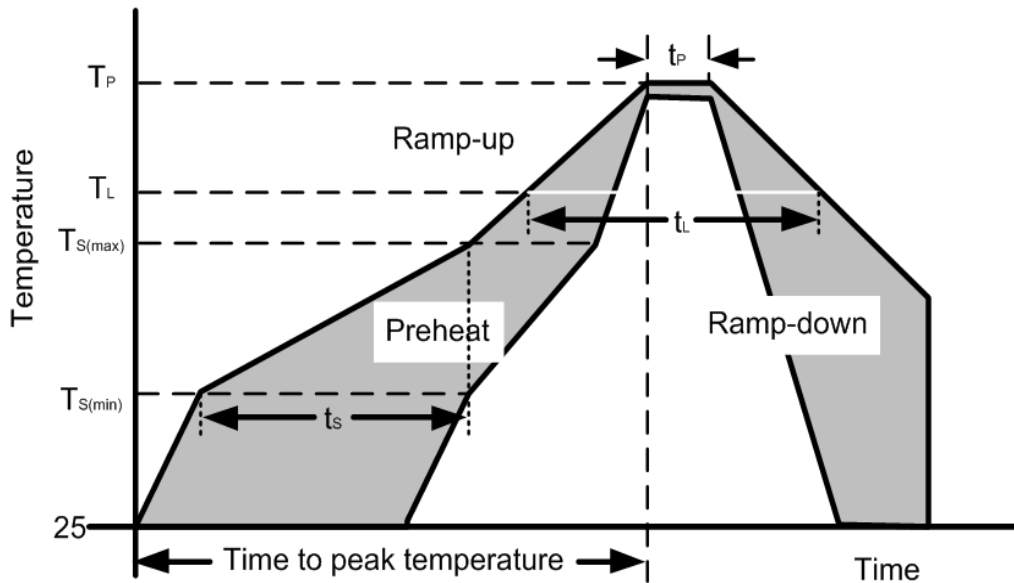


Figure 4: TLP Negative I-V Curve

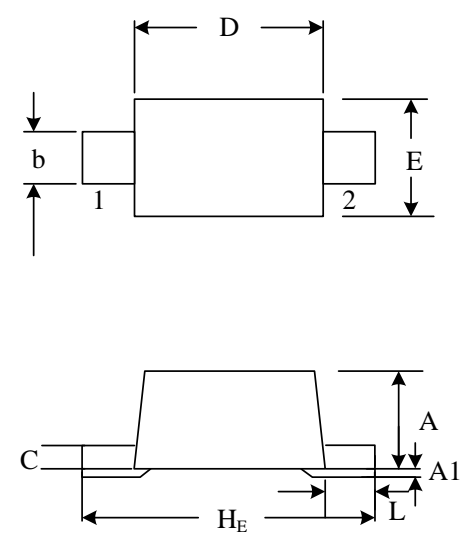



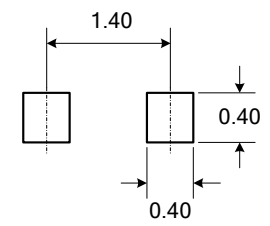
Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L —Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing – SOD-523

<p>PACKAGE OUTLINE</p> 	 <p>SOD-523</p>			
DIMENSIONS				
SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.50	0.70	0.020	0.028
A1	0.00	0.07	0.000	0.003
b	0.25	0.35	0.010	0.014
C	0.07	0.20	0.003	0.008
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
H _E	1.50	1.70	0.059	0.067
L	0.15	0.25	0.006	0.010



DIMENSIONS: MILLIMETERS

Notes:
Controlling Dimension: Millimeter.

Marking Codes

Part Number	WE05D5UC-B
Marking Code	5S

Package Information

Qty: 5k/Reel

CONTACT INFORMATION

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For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.
 The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
 Users should verify actual device performance in their specific applications.

单击下面可查看定价，库存，交付和生命周期等信息

[>>WAY-ON\(维安\)](#)